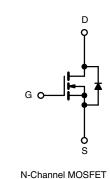


IXTH102N15T-VB Datasheet N-Channel 150 V (D-S) MOSFET

PRODUCT	SUMMARY		
V _{DS} (V)	R _{DS(on)} (Ω) MAX.	I _D (A)	Q _g (TYP.)
150	0.012 at V _{GS} = 10 V	150	113 nC
150	0.014 at Vgs= 7.5 V	135	113110







FEATURES

- Thunder power MOSFET
- Maximum 175 °C junction temperature
- 100 % $\rm R_g$ and UIS tested



FREE

APPLICATIONS

- Power supplies:
 - Uninterruptible power supplies
 - AC/DC switch-mode power supplies
 - Lighting
- Synchronous rectification
- DC/DC converter
- Motor drive switch
- DC/AC inverter
- Solar micro inverter
- Class D audio amplifier

ABSOLUTE MAXIMUM RATINGS ($T_c = 25 \text{ °C}$, unless otherwise noted)							
PARAMETER		SYMBOL	LIMIT	UNIT			
Drain-Source Voltage		V _{DS}	150	M			
Gate-Source Voltage		V _{GS}	± 20	V			
	T _C = 25 °C		150				
Continuous Drain Current ($T_J = 150 \text{ °C}$)	T _C = 125 °C	I _D	60	•			
Pulsed Drain Current (t = 100 μs)		I _{DM}	300	A			
Avalanche Current	L = 0.1 mH	I _{AS}	60				
Single Avalanche Energy ^a		E _{AS}	180	mJ			
	T _C = 25 °C	D	375 ^b	w			
Maximum Power Dissipation ^a	T _C = 125 °C		125 ^b	vv			
Operating Junction and Storage Temperature	Range	T _J , T _{stg}	-55 to +175	°C			

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	40	°C/W	
Junction-to-Case (Drain)	R _{thJC}	0.4	0/10	

Notes

a. Duty cycle \leq 1 %.

b. See SOA curve for voltage derating.

c. When mounted on 1" square PCB (FR4 material).

SPECIFICATIONS ($T_J = 25 \circ C$	C, unless ot	herwise noted)				
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	150	-	-	V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	2	-	5	V
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	-	-	± 250	nA
		$V_{DS} = 150 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	1	μA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 150 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	100	
		$V_{DS} = 150 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$	-	-	2	mA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \geq 10 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	50	-	-	А
	_	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}$	-	0.012	-	Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 7.5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$	-	0.014	-	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 20 \text{ A}$	-	52	-	S
Dynamic ^b			•	•		
Input Capacitance	C _{iss}		-	6200	-	pF
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 75 V, f = 1 MHz	-	535	-	
Reverse Transfer Capacitance	C _{rss}		-	26	-	
Total Gate Charge ^c	Qg		-	113	-	nC
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 75 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 30 \text{ A}$	-	19.5	-	
Gate-Drain Charge ^c	Q _{gd}		-	20.5	-	
Gate Resistance	R _g	f = 1 MHz	1.5	3	5	Ω
Turn-On Delay Time ^c	t _{d(on)}		-	15	30	ns
Rise Time ^c	tr	V_{DD} = 75 V, R _L = 1.25 Ω	-	114	220	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 60$ A, $V_{GEN} = 10$ V, $R_g = 1$ Ω	-	28	56	
Fall Time ^c	t _f		-	8	16	
Drain-Source Body Diode Ratings a	nd Characteri	stics ^b (T _C = 25 °C)	•	•		
Pulsed Current (t = 100 µs)	I _{SM}		-	-	200	А
Forward Voltage ^a	V _{SD}	$I_F = 30 \text{ A}, V_{GS} = 0 \text{ V}$	-	0.73	1.2	V
Reverse Recovery Time	t _{rr}		-	60	120	ns
Peak Reverse Recovery Charge	I _{RM(REC)}	I _F = 30 A, di/dt = 100 A/μs	-	10	20	А
Reverse Recovery Charge	Q _{rr}		-	0.5	1	μC

Notes

a. Pulse test; pulse width $\leq 300~\mu\text{s},$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

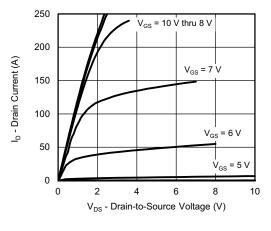
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

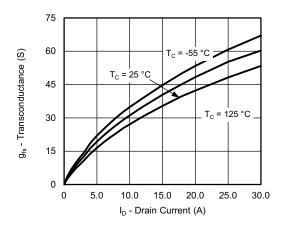
semi



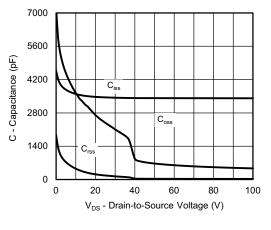
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



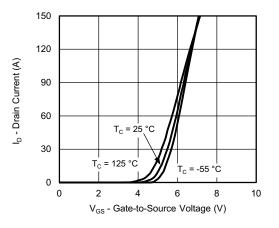
Output Characteristics



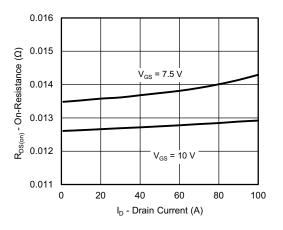
Transconductance



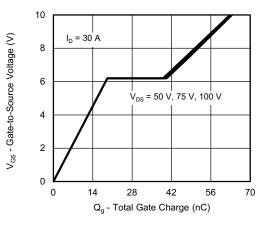
Capacitance



Transfer Characteristics



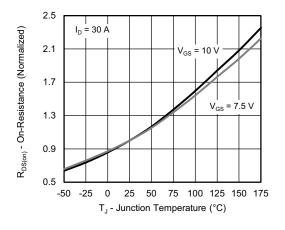
On-Resistance vs. Drain Current



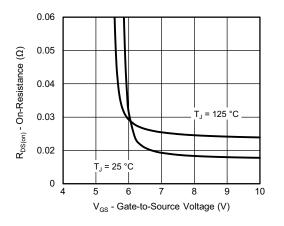
Gate Charge



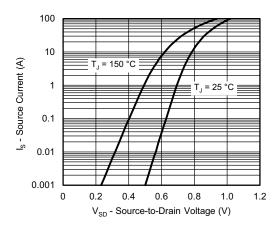
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



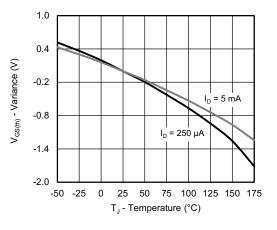
On-Resistance vs. Junction Temperature



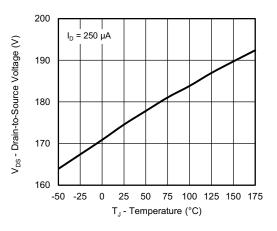
On-Resistance vs. Gate-to-Source Voltage



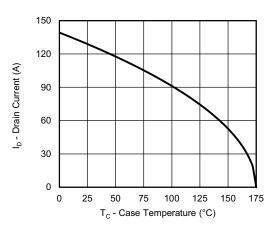
Source Drain Diode Forward Voltage



Threshold Voltage



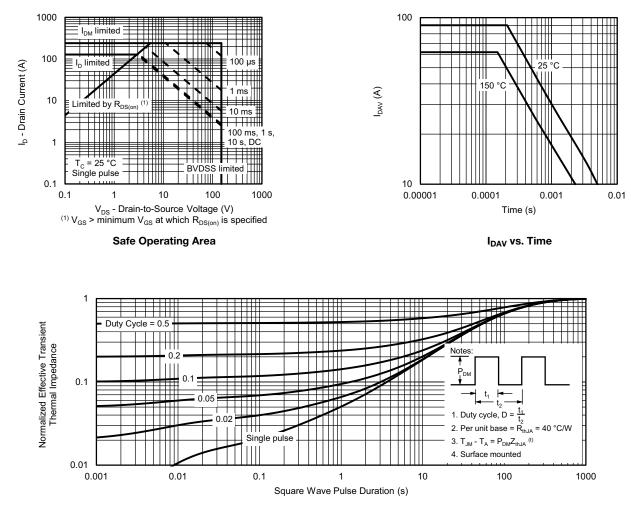
Drain Source Breakdown vs. Junction Temperature



Current De-Rating



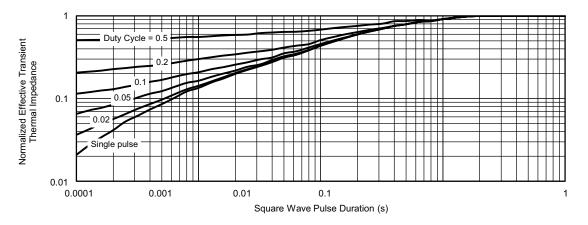
THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

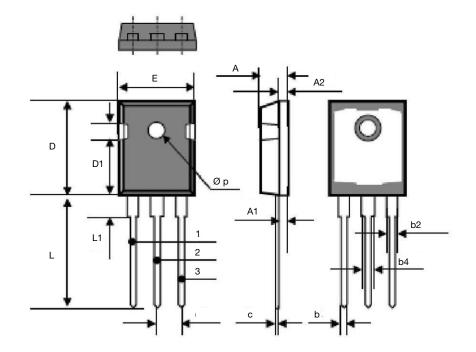
Note

- The characteristics shown in the two graphs
- Normalized Transient Thermal Impedance Junction to Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



TO-247



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
А	4.70	5.31	0.185	0.209
A1	2.21	2.59	0.087	0.102
A2	1.50	2.49	0.059	0.098
b	0.99	1.40	0.039	0.055
b2	1.65	2.41	0.065	0.095
b4	2.59	3.43	0.102	0.135
С	0.61	BSC	0.024 BSC	
D	20.80	21.46	0.819	0.845
D1	3.68	5.49	0.145	0.216
(e)	5.46 BSC		0.215 BSC	
E	15.49	16.26	0.610	0.640
L	19.81	20.32	0.780	0.800
L1	4.06	4.50	0.160	0.177
Øp	3.51	3.66	0.138	0.144



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